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### PATENTS ONLY

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Jhon Jhy Liaw

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

Name: Taiwan Semiconductor Manufacturing Co., Ltd.

Internal Address: \_\_\_\_\_

Street Address: No. 8, Li-Hsin Road 6

Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77

City: Hsin-Chu State: Zip: 300-77

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:

Assignment  Merger

Security Agreement  Change of Name

Other \_\_\_\_\_

Execution Date: October 1, 2003

4. Application number(s) or patent number(s): 10/687424

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

A. Patent Application No.(s) \_\_\_\_\_

B. Patent No.(s) \_\_\_\_\_

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David M. O'Dell

Internal Address: \_\_\_\_\_

Street Address: Haynes and Boone, LLP

901 Main Street, Suite 3100

City: Dallas State: TX Zip: 75202

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

Enclosed

Authorized to be charged to deposit account

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08-1394

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9. Signature.

David M. O'Dell  
Name of Person Signing

*David M. O'Dell*  
Signature

10-16-03  
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Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:  
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Cust. No. 27683

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10/687424  
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PATENT  
REEL: 014617 FRAME: 0120

Patent / Docket No.: 24061.39/TSMC2002-0030  
Customer No. 27683

**ASSIGNMENT**

WHEREAS, I

Jhon Jhy Liaw            of        5F, No. 111, Minshiang Street  
Hsin-Chu, Taiwan 300, R.O.C.  
Taiwan, R.O.C.

has invented certain improvements in

**A METHOD OF MANUFACTURING A  
MICROELECTRONICS DEVICE WITH ACTIVE LAYER SPACER]**

for which we have executed an application for Letters Patent of the United States of America, of even date herewith; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Inc., ("TSMC"), No. 6, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and I hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Patent / Docket No.: 24061.39/TSMC2002-0030  
Customer No. 27683

First Inventor Name:  
Residence Address:

Jhon Jhy Liaw  
5F, No. 111, Minshiang Street  
Hsin-Chu, Taiwan 300, R.O.C.  
Taiwan, R.O.C.

Dated: Oct. 1, 2003

Jhon Jhy Liaw  
Inventor Signature

Dated: \_\_\_\_\_

\_\_\_\_\_  
Witness Signature  
Witness Name: \_\_\_\_\_